

APPROVAL SHEET

承 认 书 记录编号: 版本: A

Customer 客户名称	
Part NO. 产品型号	MT230TMAK-01
Product type 产品内容	Mode: Transmissive type .Normally white. TFT LCD Module LCD Module: Graphic 220RGB*176Dot-matrix
Remarks 备注栏	□APPROVAL FOR SEPCIFICATIONS ONLY ■APPROVAL FOR SEPCIFICATIONS AND SAMPLE
Signature by Customer: 客户确认签章	<u>'</u>

设计部确认

核准	审核	定制

客户确认

核准	审核	审核

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1. General Description

MT230TMAK-01 is a 220RGB*176 dots matrix TFT LCD module. It has a TFT panel composed of 660 sources and 176 gates. The LCM can be easily accessed by micro-controller.

2. Features

Disulas Mada	Transmissive
Display Mode	a-TFT
Display Format	Graphic 220RGB*176 Dot-matrix
Input Data	3/4 Line SPI interface by MPU
Viewing Direction	6 o'clock
Drive	ILI9325D

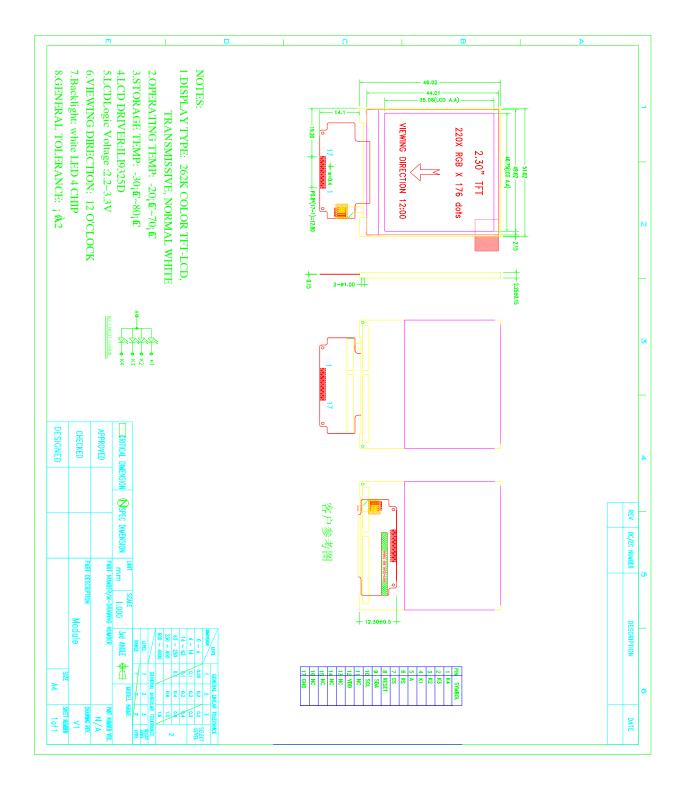
3. Mechanical Specification

Item	Specifications	Unit
Dimensional outline	51.02(W)*46.02(H)*2.25max.(T)	mm
Dimensional outline	(FPC not include)	mm
Resolution	220RGB*176	dots
LCD Active area	46.75(W)*35.06(H)	mm
Pixel size	0.2125(W)*0.2125(H)	mm

4. Mechanical Dimension

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5. Maximum Ratings

Item	Symbol	Min	Max	Unit	Note
Supply voltage	V	-0.3	4.6	V	
Operating temperature	$\mathbf{V_{T}}$	-0.3	Vcc+0.3	V	
Storage temperature	T _{OPR}	-20	70	°C	
Storage temperature	T_{STR}	-30	80	°C	

6. Electrical Characteristics

Item		Symbol	Condition	Min.	Тур.	Max.	Unit
Supply voltage	Logic	V_{CC}		2.8	3.3	3.6	V
Immut Valtage	H level	T _{IH}		0.8*IOVCC		IOVCC	V
Input Voltage	L level	T_{IL}		-0.3		0.2* IOVCC	v
Storage temp	erature	${ m I_{DD}}$	With internal voltage generation V_{CC} =2.8V; T_{emp} =25°C			TBD	mA

7. Backlight Characteristic

Item	Symbol	Min	Typical	Max	Unit
LED module Forward voltage	V_{LED}	3.0	3.2	3.4	V
LED module current	V_{LED}		60		mA
L/G Surface Luminance ★1	L_{S}	3800			Cd/m³
LCM Surface brightness uniform ★2	L_{D}	80			%

★ 1Test condition is:

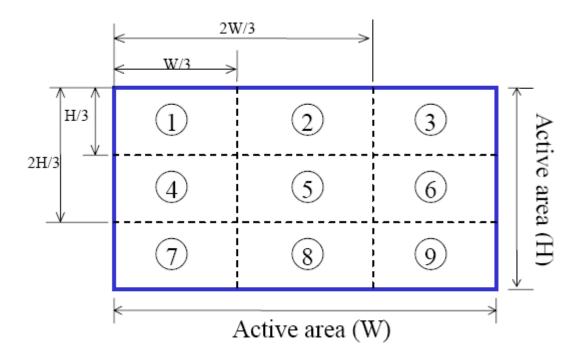
- (a) Center point on active area.
- (b)Best Contrast.

★2Uniform measure condition:

- (1)Measure 9 point. Measure location show below;
- (2)Uniform=(Min. brightness /Max. brightness)*100%
- (3)Best Contrast.

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8. Module Function Description

8.1Pin Descriptions

1	LEDK4	Cathode of Backlight	Notes
2	LEDK3	Cathode of Backlight	
3	LEDK2	Cathode of Backlight	
4	LEDK1	Cathode of Backlight	
5	LEDA	Anode of Backlight	
6	RS	Register select pin 0:Command 1:Data	
7	CS	Chip select pin	
8	RESET	LCM reset pin	
9	SDA	Serial data pin	
10	SCL	Serial clock pin	
11	NC	NC	
12	VDD	Power supply for analog (3.3V)	
13	NC	NC	
14	NC	NC	
15	NC	NC	
16	NC	NC	
17	GND	Ground	

注意: FPC 线上,R2 位置上电阻 0 欧姆,使用 4 线 SPI 串口; R1 上电阻 0 欧姆,使用 3 线 SPI 串口。 R3 上电阻 0 欧姆,表示由 11 脚做选择 3/4 线串口: PIN11=0, 3 线 SI, PIN11=1,4 线 SPI

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8.2Timing characteristics.

I80-System Interface Timing Characteristics

Normal Wrote Mode(IOVCC=1.65~3.3V,Vcc=2.4~3.3V)

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	Symbol	Unit	Min.	Typ.	Max.	Test Condition	
Due avale time	Write	t _{CYCW}	ns	100			
Bus cycle time	Read	t _{CYCR}	ns	300			
Write low-level 1	pulse width	PW_{LM}	ns	50		500	
Write high-level	pulse width	PW_{HW}	ns	50			
Read low-level p	oulse width	PW_{LR}	ns	150			
Read high -level	PW_{HR}	ns	150				
Write/ Read rise/	fall time	t _{WRr} /t _{WRt}	ns			25	
Catan time	Write(RS to nCS,E/nWR)	ns	ns	10			
Setup time	Read (RS to nCS,E/nWR)	ns	ns	5			
Address hold tim	ne	T_{AH}	ns	5			
Write data set up	t_{osw}	ns	10				
Write data hold t	t _H	ns	15				
Read data set up	t _{DDR}	ns			100		
Read data hold ti	me	t _{OHR}	ns	5			

Read Timing Characteristics

Reset Timing Characteristics(VCC=1.8~3.3V.IOVCC=1.65~3.3V)

Item	Symbol	Unit	Min.	Тур	Max
Reset low-level width	t_{RES}	ms	1		
Reset rise time	t_{RES}	μs			10

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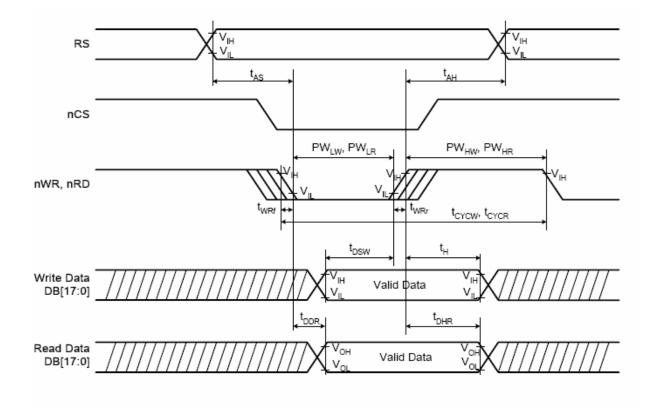


Figure 51 i80-System Bus Timing



Reset Timing

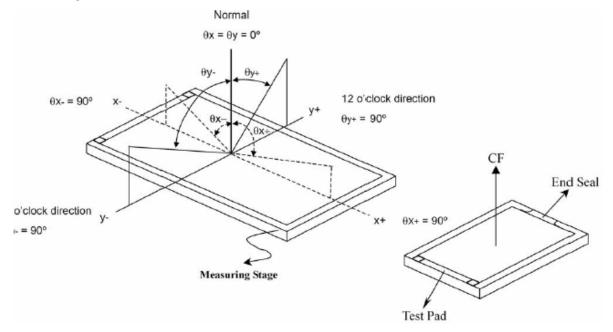
9.Electro-optical Characteristics

Item	Symbol	Conditions	Temp	Min.	Тур.	Max.	Unit	Note
Dagage Time	T_R	$\theta = \Phi = 0$	25℃		TBD	TBD	msec	NOTE2
Response Time	T_{F}				TBD	TBD		NOTEZ
Viewing Angle Range	$\Phi = 0^{\circ} (6")$	$\Phi = 90^{\circ} (3)$	")	$\Phi = 180^{\circ} \text{ (}$	12")	$\Phi = 270^{\circ}$	(9")	NOTE3
θ <u>(25°C)</u> CR≥10	TBD	TBD	7	ΓBD		TBD		NOTE3

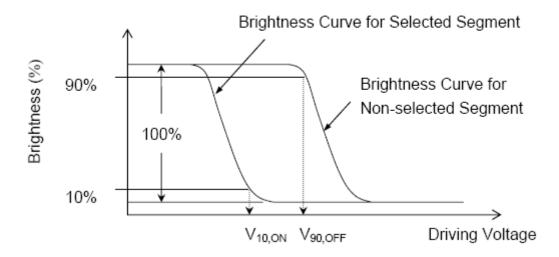
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The above "viewing angle" is the measuring position with the largest contrast ratio. Not for good image quality. Viewing direction for good image quality is 12 O'clock.

- For panel only
- Electro-Optical Characteristics Test Method



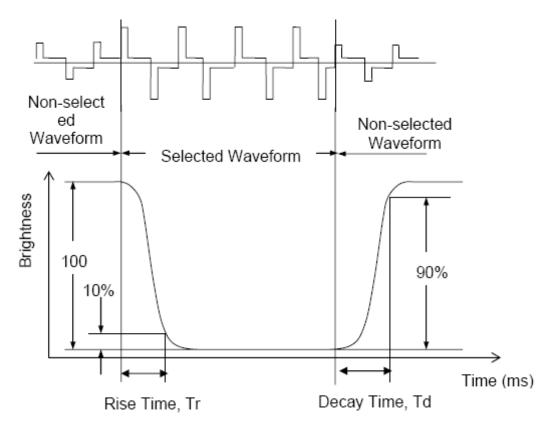
$$Vop = (V_{10, ON} + V_{90, OFF})/2$$



.Note2.Definition of Optical Response Time:

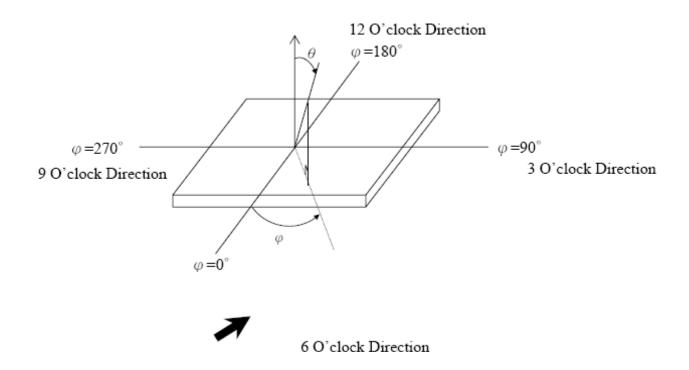
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.Note3.Definition of Viewing Angle θ and Φ :

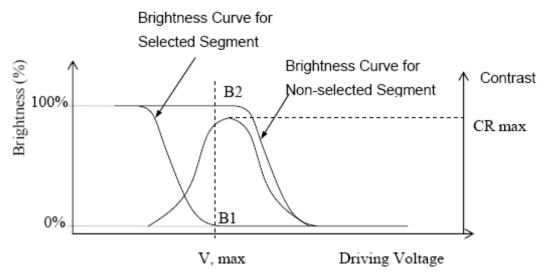




Note4.Definition of Contrast ratio (CR):



CR = Brightness of Non-selected Segment (B2) Brightness of Selected Segment (B1)



10. Reliability10.1Mtbf

The LCD module shall be designed to meet a minimum MTBF value of 50000 hours with normal

10.2Test condition

NO.	ITEM	CONDITION	CRITERION
1	High Temperature Non-Operating Test	80°C*240Hrs	No Defect Of Operational
2	Low Temperature Non-Operating Test	-30°C*240Hrs	Function In Room Temperature
3	High Temperature/Humidity Non Operating Test	60°C*90%RH*240Hrs	Are Allowable
4	High Temperature Operating Test	70°C*240Hrs	。 IDD of LCM in Pre-and
5	Low Temperature Operating Test	-20℃*240Hrs	Post-Test Should Follow
	Thermal Charle Test	-20 °C (30Min) ν70 °C (30Min)	Specification
6	Thermal Shock Test	*10CYCLES	

Notes:

- 1. Judgments should be made after exposure in room temperature for two hours.
- 2. The distill water is used for the high temperature/humidity test.
- 3. The sample above is individually for every reliability tests condition.

11.Inspection standards

1.AQL(Acceptable Quality Level

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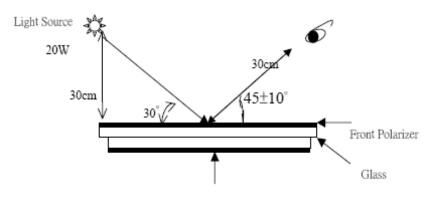
AQL of major and minor defect.

	MAJOR DEFECT	MINOR DEFECT
AQL	0.65	1.5

2. Basic conditions for inspection

The LCM face to us, in normal environment, the lux is 1000 ± 200 .(Darkroom's lux: 100 ± 50), About an angle of incidence 30, a distance of 30 cm with an angle of 45 degree to check the products without uncovering the film!

(As shown below)



Rear Polarizer

3.Inspection item and criteria

3.1 Visual inspection criterion in immobility

3.1.1Glass defect

NO	Defect item	Criteria	Remark
1	Dimension Unconformity (Major defect)	By Engineering Drawing	
2	Cracks (Major defect)	 Linear cracks panel Reject Nonlinear crack contrast by limited sample 	
3	Glass extrude the conductive area (minor defect)	a: disregards and no influence assemblage. 1) b≤1/3Pin width(non bonding area) 【Accept】 2)bonding area≤0. 5mm 【Accept】	A: Length, b: Width
4	Pin-side ,conductive area damaged (minor defect)	(a c: disregards) b≤1/3of effective length for bonding electrode	a: length, b: Width, c: Thickness

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		【Accept】	T D
	Pin-side,non-conductive	1)Damage area don't touch the ITO	a: Length, b: Width c: Thickness
	area damaged	(Inclueling contraposition mark,	//
	(minor defect)	except scribing mark)	
		【Accept】	\\ \\ \lambda \lambda
5		$2)$ C $<$ T b \leq BM1/3of width	a l
		[Accept]	
		3)c=T	b a c
		b not touch the seal glue	
		[Accept]	
	NY ' '1 1	4)a disregards	TTI: 1 1 11 C
	Non-pin-side damage	c <t< th=""><th>c: Thickness b: width of</th></t<>	c: Thickness b: width of
	(minor defect)	1)b exceeds 1/3Bm	
		【Reject】	DW et all
6			BM內緣
		b not touch the seal glue [Reject]	
			damage b

3.1.2LCD appearance defect(View area)

NO	Defect item	Criteria		Remark
		Specification	Allowable	note1:L: Length, W: Width
	Fiber gless	W ≤ 0.03mm	disregard	note2: disregard if out of AA
1	Fiber、glass cratch、polarizer scratch/folded (minor defect)	0.03mm <w≤0.05mm; L≤3.0mm</w≤0.05mm; 	2	\top \top \top \top \top \top \top \top
		0.05mm <w≤0.1mm; L≤3.0mm</w≤0.1mm; 	1	
		W>0.1mm;L>3.0mm	0	W
	Polarizer bubble	φ ≤ 0.2mm	disregard	note1: $\Phi = (L+W)/2$, L:Length,
2		0.2 mm $< \Phi \le 0.3$ mm	2	W :Width
2	concave and convex (minor defect)	0.3 mm $< \Phi \le 0.5$ mm	1	note2:disregard if out of AA
	(minor defect)	0.5mm< φ	0	
3	Black dots, dirty dots,	φ ≦ 0.15mm	disregard	note2:disregard if out of AA
	impurities, eye winker	0.15 mm $< \phi \le 0.25$ mm	2	

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	(minor defect)	0.25 mm $< \phi \le 0.3$ mm	1	
		0.3mm< φ	0	φ φ
		φ ≤ 0.1mm	disregard	note1: $\Phi = (L+W)/2$, L=Length,
4	Polarizer prick	0.1 mm $< \Phi \le 0.25$ mm	3	W=Width
4	(minor defect)	φ>0.25mm	0	note2:the distance between two
	Ψ / 0. 25 ιι ιι ι		Ü	dots>5mm

3.1.3FPC

NO	Defect item	Criteria		Remark
	Copper screen peel	Copper screen pe	el	
1	(minor defect)	【Reject】		
2	No release tape or peel	No release tape o	r peel	
2			【Reject】	
	Dirty dot and impurity of FPC	Specification	Allowable	Note1: Cannot have stride
3	for customer using side	Φ ≦ 0.25mm	2	ITO impurities
	(minor defect)	Ф>0. 25	0	

3.1.4Black tape &Mara tape

NO	Defect item	Criteria	Remark
	FPC or H/S black tape	1. shift spec:	LCD
		1) glue to the polarize	
		【Reject】	<u>↓</u> <u>×</u>
1	(minor defect)	2) IC bare 【Reject】	y1
1		2. left-and-right spec:	
		1)exceed of FPC edge or	Mara tape
		H-S edge 【Reject】	x1
		2) IC bare 【Reject】	Heat Seal
2	No black tape	No black tape	
2	(major defect)	【Reject】	
3	Tape position mistake	Not by engineering drawing	
3	(minor defect)		
	Mara tape defect	Peel before pulling the	
4	(minor defect)	protecting film	
		【Reject】	

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3.1.5Silicon and Taffy glue

NO	Defect item	Criteria	Remark
1	Quantity of silicon	Uncover the ITO and circuit area	note: compared by engineering
	(major defect)	【Reject】	
2	Taffy glue	1.Uncover the reveal copper area [Reject]	note: if customer has special
	(major defect)	2.Cover layer 0.3mm(Min)~3.0mm(Max)	requirement, refer to the technical
		【Reject】	document
			3.0mm(Max)
3	Depth of glue covering	Depth of glue covering overtop front	Except of the special requirement
	(major defect)	Polarizer 【Reject】	

3.2Electrical criteria

NO	Defect item	Criteria	Remark
1	No display	No display	
	(major defect)	【Reject】	
2	Missing line	Missing line	
	(major defect)	【Reject】	
3	Seg-com light and dark	Seg-com light and dark	ND filter 2% test
	(major defect)	【Reject】	
4	No display in immobility	No display in immobility	
	(major defect)	【Reject】	
5	Flicker of Pattern	Flicker of Pattern	
	(major defect)	【Reject】	
6	Mura	ND filter 2%test	
	(major defect)		
7	Over current	Over current	
	(major defect)	【Reject】	
8	Voltage out of specification	Voltage out of	
	(major defect)	specification	
		【Reject】	
9	Pattern blur, error code	Pattern blur, error code	
	(major defect)	【Reject】	
10	Dark light, Flicker	Dark light, Flicker	
	(major defect)	【Reject】	
11	Black/white dots , Dirty	Specification	Allowable Note1:disregard if out of AA

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	dots, eye winker	φ ≦0.15mm	disregard	· · · · · · · · · · · · · · · · · · ·
	(major defect)	0.15 mm $< \Phi \le 0.25$ mm	2	\bigcirc $\downarrow \phi$
		0.25 mm $< \phi \le 0.3$ mm	1	-
		0.3mm< φ	0	ψ
12	Fiber glass crutch Polarizer	W ≤ 0.03mm	disregard	Note1:L: Length, W: Width
	scratch/folded	$0.03 \text{mm} < W \le 0.0.05 \text{mm}$	2	Note2: disregard if out of AA
	(major defect)	L≤3.0mm	2	← т →
		0.05 mm $<$ $\mathbb{W} \leq 0.1$ mm	1	
		L≤3.0mm	1	V X
		W>0.1mm;L>3.0mm	0	w

12.Precautions for using LCD modules.

12.1 Safety

- (1)Do mot swallow any liquid crystal ,even if there is no proof that liquid crystal is poisonous.
- (2)If the LCD panel breaks, be careful not to get liquid crystal to touch your skin.
- (3)If skin is exposed to liquid crystal, wash the area thoroughly with alcohol or soap.

12.2Srorang Conditions

- (4)Store the panel or module in a dark place where the temperature is 23 ± 5 °C and the humidity is below 45 ± 20 %RH.
- (5) Store in anti-static electricity container.
- (6) Store in clean environment, free from dust, active gas, and solvent.
- (7) Do not place the module near organics solvents or corrosive gases.
- (8))Do not crush, shake, or jolt the module.

12.3Handling Precautions

- (9) Avoid static electricity, which can damage the CMOS LSI.
- (10) The polarizing plate of the display is very fragile, please handle if very carefully.
- (11) Do not give external shock.
- (12) DO mot apply excessive force on the surface.
- (13)Bo not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- (14)Do not use ketonics solvent & Aromatic solvent, use with a soft cloth soaked with a

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cleaning naphtha solvent.

(15) Do not operate it above the absolute maximum rating.

(16)Do not remove the panel or frame from the module.

12.4Warranty

The period is within twelve months since the date of shipping out under normal using and storage conditions.

13.Factory

FACTORY NAME:

FACTORY ADDRESS:

FACTORY PHONE:

14. Revision history

Version	Revise record	Date
A	Original version	2010-11-27